



Heisener.com

550-10-500M30-001152 Information

Part Number 550-10-500M30-001152

Manufacturer Preci-Dip

Category Connectors, Interconnects

Sockets for ICs, Transistors

Description BGA SOLDER TAIL

Package

For the pricing/inventory/lead time, please contact

Website: https://www.heisener.com For Reference Only

E-mail: salesdept@heisener.com



Request a Quote

Certified Quality

Heisener's commitment to quality has shaped our processes for sourcing, testing, shipping, and every step in between. This foundation underlies each component we sell.









550-10-500M30-001152 Specifications

Manufacturer Part Number	550-10-500M30-001152
Manufacturer	Preci-Dip
Category	Connectors, Interconnects
	Sockets for ICs, Transistors
Package	-
Series	550
Type	BGA
Number of Positions or Pins (Grid)	500 (30 x 30)
Pitch - Mating	0.050" (1.27mm)
Contact Finish - Mating	Gold
Contact Finish Thickness - Mating	10μin (0.25μm)
Contact Material - Mating	Brass
Mounting Type	Through Hole
Features	Closed Frame
Termination	Solder
Pitch - Post	0.050" (1.27mm)
Contact Finish - Post	Gold
Contact Finish Thickness - Post	10μin (0.25μm)
Contact Material - Post	Brass
Housing Material	FR4 Epoxy Glass
Operating Temperature	-55°C ~ 125°C
	Report errors?

550-10-500M30-001152 Guarantees



Quality Guarantees

We provide 90 days warranty. *

If the items you received were not in perfect quality, we would be responsible for your refund or replacement, but the items must be returned in their original condition.



Service Guarantees

We guarantee 100% customer satisfaction.

Our experienced sales team and tech support team back our services to satisfy all our customers.

550-10-500M30-001152 Payment Methods



















550-10-500M30-001152 Shipping Methods













If you have any question about 550-10-500M30-001152, please do not hesitate to contact us!

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